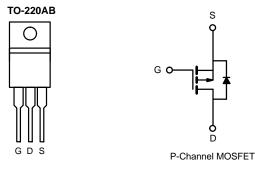


# P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY		
V <sub>DS</sub>	-100	V
$R_{DS(on)}$ $V_{GS} = 10$ V	167	mΩ
$R_{DS(on)}$ $V_{GS} = 4.5$ V	178	mΩ
I <sub>D</sub>	-18	А
Configuration	Sin	gle



#### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- Power Switch
- · Load Switch in High Current Applications
- DC/DC Converters

ABSOLUTE MAXIMUM RATING	<b>S</b> (T <sub>C</sub> = 25 °C, unless oth	erwise noted)			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
Continuous Drain Current ( $T_1 = 150 \ ^{\circ}C$ )	T <sub>C</sub> = 25 °C	1-	- 18		
Continuous Drain Current $(1) = 150$ C)	T <sub>C</sub> = 70 °C	– I <sub>D</sub> –	- 13	А	
Pulsed Drain Current (t = 300 µs)		I <sub>DM</sub>	- 100	A	
Avalanche Current		I <sub>AS</sub>	- 10		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	31	mJ	
	T <sub>C</sub> = 25 °C		11.7 <sup>b</sup>		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	– P <sub>D</sub> –	1.1	W	
Operating Junction and Storage Temperature Ra	Operating Junction and Storage Temperature Range		- 55 to 150	°C	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	60	°C/W
Junction-to-Case (Drain)	R <sub>thJC</sub>	9	C/W

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 V, I_{D} = -250 \mu A$	- 100			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	- 1		- 2.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μA	
		V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			- 250	μA A	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le$ - 10 V, $V_{GS}$ = - 10 V	- 18			А	
	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 14 A		167		0	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 12 A		178		mΩ	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 20 V, I <sub>D</sub> = - 14 A		20		S	
Dynamic <sup>b</sup>	•						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 20 V, f = 1 MHz		1460			
Output Capacitance	C <sub>oss</sub>			330			
Reverse Transfer Capacitance	C <sub>rss</sub>			280			
Total Gate Charge <sup>c</sup>	Qg			67	100		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -14 \text{ A}$		13.5		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			14			
Gate Resistance	Rg	f = 1 MHz	0.5	2.5	5	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = - 20 V, $R_L$ = 2 $\Omega$		11	20		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		42	63	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			12	20		
Drain-Source Body Diode Ratings an	nd Characteri	stics T <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	۱ <sub>S</sub>				- 18		
Pulsed Current	I <sub>SM</sub>				- 100	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 10 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			38	57	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 10 A, dI/dt = 100 A/μs		2.3	3.5	А	
Reverse Recovery Charge	Q <sub>rr</sub>	1 F		40	60	nC	

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

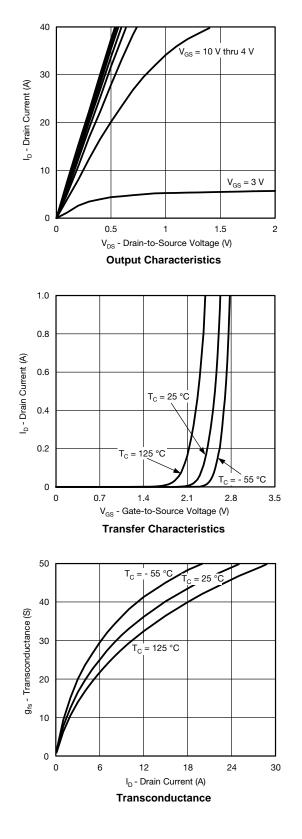
c. Independent of operating temperature.

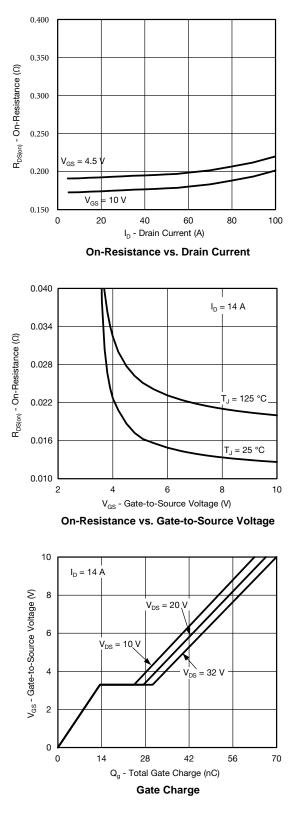
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

emi



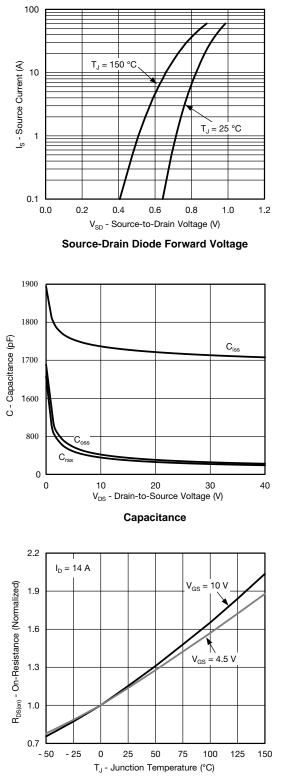
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



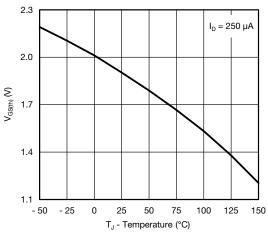




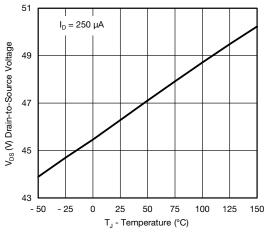
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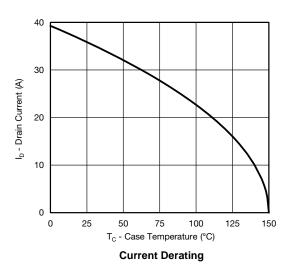
On-Resistance vs. Junction Temperature



Threshold Voltage

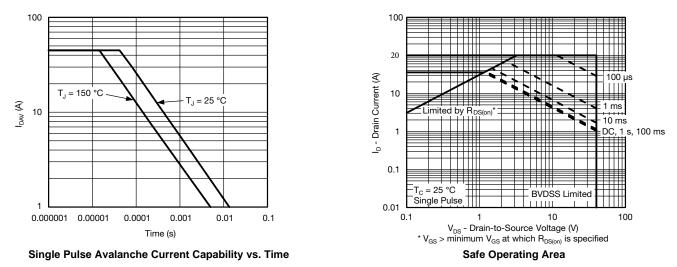


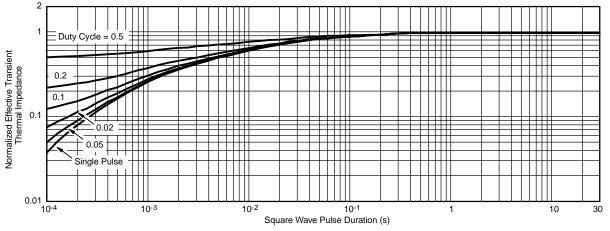
Drain Source Breakdown vs. Junction Temperature





### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

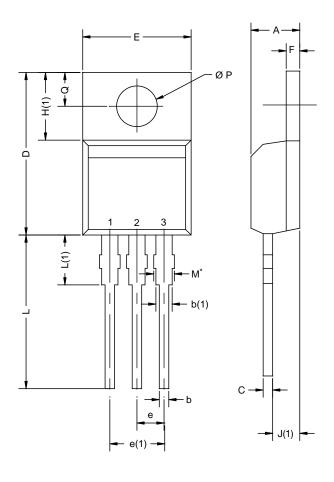




Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-220AB**



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

#### Notes

\* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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